



Material Content Data Sheet



Sales Product Name		IPB80N04S3-04		Issued		29. August 2013			
MA#		MA000366353							
Package		PG-TO263-3-2		Weight*		1463.64 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.719	0.32	0.32	3224	3224	
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		583		
	inorganic material	phosphorus	7723-14-0	0.256	0.02		175		
	non noble metal	copper	7440-50-8	851.691	58.18	58.26	581901	582659	
wire	non noble metal	aluminium	7429-90-5	5.867	0.40	0.40	4009	4009	
encapsulation	organic material	carbon black	1333-86-4	8.800	0.60		6012		
	plastics	epoxy resin	-	96.796	6.61		66133		
	inorganic material	silicondioxide	60676-86-0	481.045	32.87	40.08	328663	400808	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6598	6598	
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156	
solder	noble metal	silver	7440-22-4	0.093	0.01		64		
	non noble metal	tin	7440-31-5	0.075	0.01		51		
	non noble metal	lead	7439-92-1	3.558	0.24	0.26	2431	2546	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com